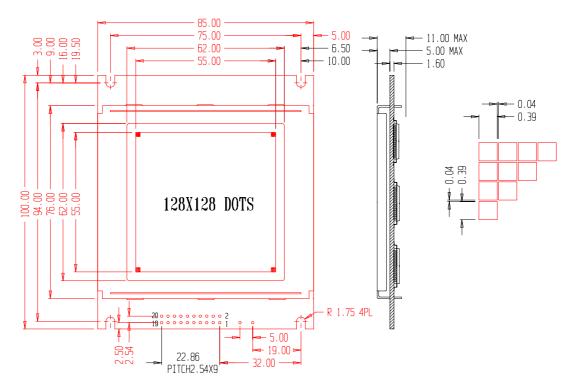
PRODUCT SPECIFICATIONS

- PHYSICAL DATA
- EXTERNAL DIMENSIONS
- BLOCK DIAGRAM
- ABSOLUTE MAXIMUM RATINGS
- ELECTRICAL CHARACTERISTICS
- OPERATING PRINCIPLES & METHODS
- DISPLAY DATA RAM ADDRESS MAP
- ELECTRO-OPTICAL CHARACTERISTICS
- INTERFACE PIN CONNECTIONS
- PART LIST
- CIRCUIT DIAGRAM
- RELIABILITY
- QUALITY GUARANTEE
- INSPECTION CRITERIA
- PRECAUTIONS FOR USING LCD MODULES
- USING LCD MODULES

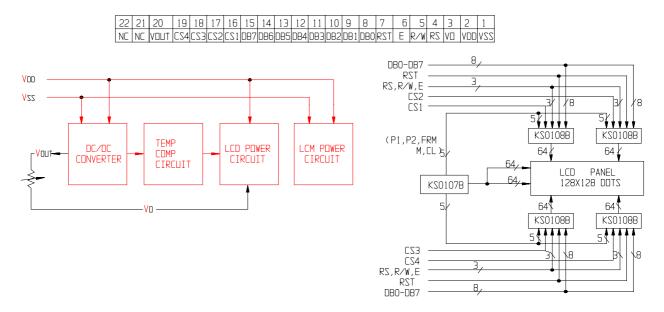
PHYSICAL DATA

Item	Contents	Unit
LCD type	STN	
LCD duty	1/64	
LCD bias	1/9	
Viewing direction	6	o'clock
Module size (W×H×T)	85 × 100 × 11/14MAX (3.35" × 3.94" × 0.43"MAX)	mm
Viewing area (W×H)	62 × 62 (2.44" × 2.44")	mm
Number of dots	128×128	dots
Dot size (W×H)	$0.39 \times 0.39 \ (0.015'' \times 0.015'')$	mm
Dot pitch (W×H)	0.43 × 0.43 (0.017" × 0.017")	mm

EXTERNAL DIMENSIONS



BLOCK DIAGRAM



LCD MODULE

Parameter	Symbol	Min	Max	Unit
Supply voltage for logic	VDD	-0.3	7.0	V
Supply voltage for LCD	VDD - VO	VDD-19.0	VDD+0.3	V
Input voltage	VI	-0.3	VDD+0.3	V
Operating temperature	TOP	0	50	°C
Storage temperature	TST	-10	60	°C

ABSOLUTE MAXIMUM RATINGS ($Ta = 25^{\circ}C$)

ELECTRICAL CHARACTERISTICS (VDD = $+5V\pm10\%$, VSS = 0V, Ta = 25° C)

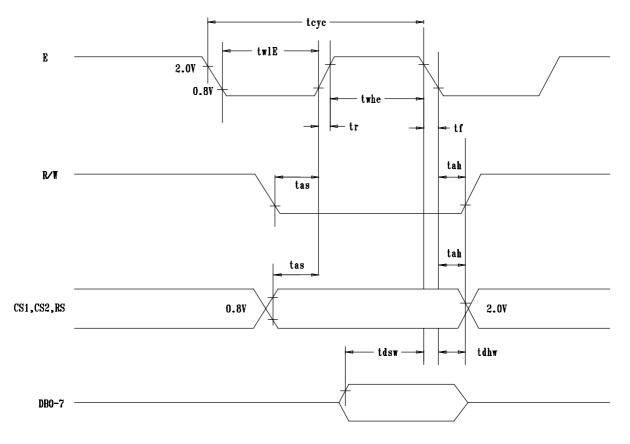
♦ DC Characteristics

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Supply voltage for logic	VDD		4.5	5.0	5.5	V
Supply current for logic	IDD			11.9	20	mA
		0°C	12.1	12.8	13.5	V
Operating voltage for LCD	VDD - VO	25°C	11.9	12.6	13.3	V
		50°C	11.6	12.3	13.0	V
Input voltage ' H ' level	VIH		2.0		VDD	V
Input voltage ' L ' level	VIL		0		0.8	V

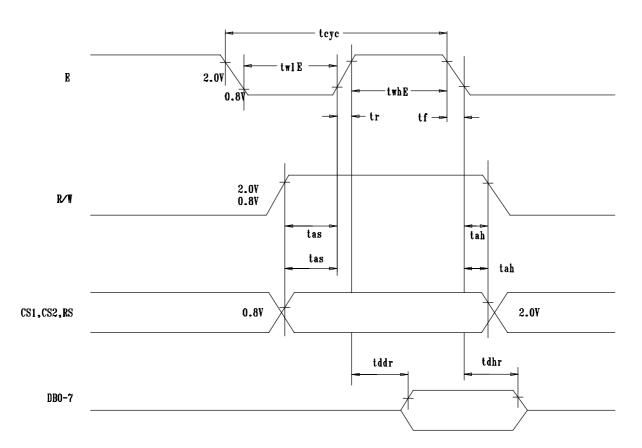
♦ AC Characteristics

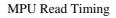
• MPU Interface

Characteristic	Symbol	Min.	Тур.	Max.	Unit
E cycle	tcyc	1000			ns
E high level width	twh _E	450			ns
E low level width	twl _E	450			ns
E rise time	t _r			25	ns
E fall time	t _f			25	ns
Address set-up time	t _{as}	140			ns
Address hold time	t _{ah}	10			ns
Data set-up time	tdsw	200			ns
Data delay time	tddr			320	ns
Data hold time(write)	tdhw	10			ns
Data hold time(read)	tdhr	20			ns



MPU Write Timing





■ OPERATING PRINCIPLES & METHODS

♦ I/O Buffer

Input buffer controls the status between the enable and disable of chip. Unless the CS1 or CS2 is in active mode, input or output of data and instruction do not execute. Therefore internal state is not change. But RSTB can operate regardless of CS1 and CS2.

♦ Input Register

Input register is provided to interface with MPU which is different operating frequency. Input register stores the data temporarily before writing it into display data RAM.

When CS1 or CS2 is in the active mode, R/W and RS select the input register. The data from MPU is written into input register and then write it into display data RAM. Data is latched when falling of the E signal and written automatically into the display data RAM by internal operation.

♦ Output Register

Output register stores the data temporarily from display data RAM when CS1 or CS2 is in active mode and R/W and RS = H. Stored data in display data RAM is latched in output register. When CS1 or CS2 is in active mode and R/W = H, RS = L, status data (busy check) can be read out.

To read the contents of display data RAM, twice access of read instruction is needed. In first access, data in display data RAM is latched into output register. In second access, MPU can read data which is latched. That is, to read the data in display data RAM, it needs dummy read. But status read does not need dummy read.

RS	R/W	Function
0	0	Instruction
	1	Status read (busy check)
1	0	Data write (from input register to display data RAM)
	1	Data read (from display data RAM to output register)

♦ Reset

System reset can be initialized by setting RST terminal at low level when turning power on, receiving instruction from MPU. When RST becomes low, following procedure is occurred.

1. Display off

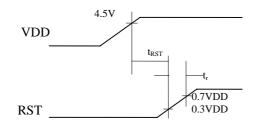
2. Display start line register become set by 0. (Z-address 0)

While RST is low level, no instruction except status read can be accepted. Reset status appears at DB4. After DB4 is low, any instruction can be accepted.

The Conditions of power supply at initial power up are shown in table 1.

 Table 1. Power Supply Initial Conditions

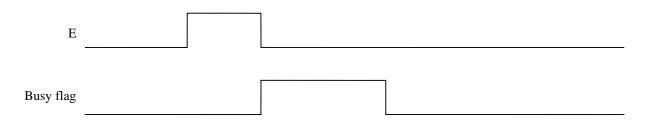
Item	Symbol	Min.	Тур.	Max.	Unit
Reset time	t _{RST}	1.0			us
Rise time	t _r			200	ns



♦ Busy Flag

Busy flag indicates that KS0108B is operating or not operating. When busy flag is high, KS0108B is in internal operating. When busy flag is low, KS0108B can accept the data or instruction.

DB7 indicates busy flag of the KS0108B.



♦ Display On/Off Flip-Flop

The display on/off flip-flop makes on/off of the liquid crystal display. When flip-flop is reset (logical low), selective voltage or non selective voltage appears on segment output terminals. When flip-flop is set (logical high), non selective voltage appears on segment output terminals regardless of display RAM data.

The display on/off flip-flop can changes status by instruction. The display data at all segment disappear while RSTB is low. The status of the flip-flop is output to DB5 by status read instruction.

♦ X Page Register

X page register designates page of the internal display data RAM. It has not count function. An address is set by instruction.

♦ Y Address Counter

Y address counter designates address of the internal display data RAM. An address is set by instruction and is increased by 1 automatically by read or write operations of display data.

♦ Display Data RAM

Display data RAM stores a display data for liquid crystal display. To express on state of dot matrix of liquid crystal display, write data 1. The other way, off state writes 0.

 $DB<0:7>=0 \rightarrow Y \text{ address } 0 \rightarrow S1$ $DB<0:7>=63 \rightarrow Y \text{ address } 63 \rightarrow S64$

♦ Display Start Line Register

The display start line register indicates address of display data RAM to display top line of liquid crystal display. Bit data (DB<0:5>) of the display start line set instruction is latched in display start line register. It is used for scrolling of the liquid crystal display screen.

♦ Display Control Instruction

The display control instructions control the internal state of the KS0108B. Instruction is received form MPU to KS0108B for the display control. The following table shows various instructions.

Instruction	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Function
Display ON/OFF	0	0	0	0	1	1	1	1	1	0/1	Controls the display on or off.
											Internal status and display RAM
											data are not affected.
											0:OFF, 1:ON
Set Address	0	0	0	1		Y	addres	s (0~6	3)		Sets the Y address in the Y
											address counter.
Set Page	0	0	1	0	1	1	1		Page		Sets the X address at the X
(X address)									(0~7)		address register.
Display Start Line	0	0	1	1		D	Display	start lir	ne		Indicates the display data RAM
							(0~	63)			displayed at the top of the screen.
Status Read	0	1	В	0	0	R	0	0	0	0	Read status.
			U		Ν	Е					BUSY 0 : Ready
			S		/	S					1 : In operation
			Y		0	E					ON/OFF 0 : Display ON
					F	Т					1 : Display OFF
					F						RESET 0 : Normal
											1 : Reset
Write Display Data	1	0				Write	e Data				Writes data (DB0:7) into display
											data RAM. After writing
					instruction, Y address is increase						
					by 1 automatically.						
Read Display Data	1	1			Read Data Reads data (DB0:7) from display						
											data RAM to the data bus.

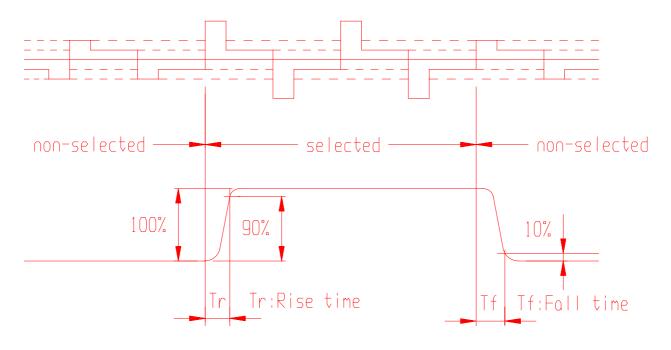
DISPLAY DATA RAM ADDRESS MAP

PAR A HUNE No Call Bay loop Call Bay loop Addition Addit	COMMON
Bit a base of the second secon	COMIO
B3 B3 C3 C4 B5 C4 C4 B5 C4 C5 D7 C4 C5 D2 C4 C6 D7 C4 C6 D7 C4 C6 D7 C4 C6 D2 C3 C6 D2 C3 C4 D2 C3 C4 D2 C3 C4 D2 C3 C6 D2 C3 C6 D3 C6 C2 D4 C8 C7 D5 C7 C2 D4 C8 C2 D5 C1 C8 D6 C1 C8 D7 C8 C9 D7 C8 C9 D7 C8 C9 D7 C8	COM 1
D 0	COM 2
B5 I + D <thi +="" d<="" th=""> <thi +="" d<="" th=""> <thi +="" d<="" td=""><td>COM 3 COM 4</td></thi></thi></thi>	COM 3 COM 4
B7 I	COM 4
B0 B0 CB CB <td< td=""><td>COM 6</td></td<>	COM 6
B0 1	COM 7
B0 1	COM 8 COM 9
	COM 10
B6 C D C D C D C D	COM 11
D 6 I I I I I I I I I I I I I I I D 0	COM 12 COM 13
0.7 0.0 0	COM 13
BA D1 D2 D3 D4 D4 D5 D6 D7 D7 D7 D7 D8 D8 D9 D9 </td <td>COM 15</td>	COM 15
BA D2 D2 D3 D4 D5 D6 D7 D7 D7 D7 D7 D7 D6 D6 D7 D7 D6 D6 D7 D7 D7 D7 D7 D7 D7 D7 D7 D7 D7 D7 D7	COM 16
BA D3 I	COM 17 COM 18
B4	COM 10
B6 I	COM 20
BB D 7 I I I I I I I D 7 BB D 1 I I I I I I I D 9 BC D 3 I I I I I I I D 9 D 4 D 0 D 0 D 0 D 5 I I I I I I D 0 D 0 D 6 I I I I I I I D 0 D 0 D 6 I I I I I I I D 0 D 0 D 7 I I I I I I I D 0 D 0 D 1 I I I I I I I D 0 D 0 D 2 I I I I I I I I D 0 D 0 D 4 I I I I I I I D 0 D 0 D 4 I I I I I I I I I D 0 D 0 D 4 I I I I I I I I I D 0 D 0 D 4 I I I I I I I I I I D 0 D 0 D 4 I I I I I I I I I I I I D 0 D 0 D 5 I I I I I I I I I I I I I I I I I D 0 D 0 D 4 I I I I I I I I I I I I I I I I I I I	COM 21 COM 22
BB 0	COM 22 COM 23
BB	COM 24
BB 0.4 0.6 0.0 0.0 0.6 0.6 0.0 0.0 0.0 0.7 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.0 0.	CON 25
bb 04 1 1 0	COM 26 COM 27
B6 I	COM 28
$BC = \begin{bmatrix} 0 & 7 & & & & & & & & & & & & & & & & &$	COM 29
BC B0 B	COM 30 COM 31
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	COM 32
BC 0.3 0.4 0.1 0.1 0.1 0.5 0.	COM 33
$BP = \begin{bmatrix} 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0$	COM 34 COM 35
D 5 B	COM 35
D7 I I I I I I I I I I I E7 E7 D0 I I I I I I I I E8 E9 D1 D1 E7 E8 D1 E7 E8 E9 D2 D3 E1 E8 E9 D4 D5 E7 E8 E7 D6 D4 E7 E8 E7 D6 D7 I I I I E7 E8 D7 I I I I I E7 E8 E7 B8 D4 E7 E7 E7 E7 D6 I I I I I I I I I I I I F7 E7 E7 B8 D4 I I I I I I I I F7 F7 F7 B7 D6 I I I I I I I I I I F7 F7 B7 D7 I I I I I I I I I I F7 F7 B7 D7 I I I I I I I I I I I I I F7 F7 B7 D3 I I I I I I I I I I I I I I I I I I I	COM 37
B0 B	COM 38 COM 39
BD D 2 0	COM 35
BD D3 I I I I I I I B B C B B C B D B D B D B D B D B B B D B D B D	COM 41
BB D 4 E C D 6 D 6 B D D 7 I I I I I I I B P D 0 F 0 P 1 D 1 I I I I I I I I P 3 D 3 I I I I I I I I P 4 D 5 I I I I I I I I P 5 D 6 P 7 P 4 D 7 I I I I I I I I P 3 BF D 0 P 4 D 1 I I I I I I I I I P 5 P 6 P 7 P 6 P 7 P 7 P 6 P 7 P 7 P 7 D 0 I I I I I I I I P 7 D 1 I I I I I I I I I P 7 D 2 I I I I I I I I I I P 7 D 1 I I I I I I I I I I I I P 7 D 2 I I I I I I I I I I I I I I I I I I I	COM 42 COM 43
BE B	COM 43
D 7 I I F0 F1 D 0 I F2 F3 F2 D 4 I I F2 F3 D 4 I I F6 F2 D 6 I I F6 F6 D 7 F6 F6 F6 D 7 F7 F6 F6 D 7 F7 F7 F6 D 7 F7 F7 F7 D 0 I I F7 F7 D 1 F7 F7 F7 F7 D 1 F7 F7 F7 F7 D 1 F7 F7 F7 F7 D 2 I I I F7 F7 D 3 I I I F7 F7 D 4 I I I F7 F7 D 5 I I I I F7 D 6 I I I I I F7 D 6 I	COM 45
BB D 0 D 1 D 2 D 3 D 4 D 4 D 5 D 6 D 7 D 7 D 0 D 1 D 4 D 4 D 5 D 6 D 7 D 7 D 0 D 1 D 2 D 7 D 7 D 0 D 1 D 2 D 7 D 0 D 1 D 2 D 3 D 4 D 7 D 7 D 0 D 1 D 2 D 3 D 4 D 7 D 7 D 0 D 1 D 2 D 3 D 4 D 1 D 7 D 7 D 0 D 1 D 2 D 3 D 4 D 1 D 7 D 7 D 0 D 1 D 1 D 2 D 3 D 1 D 7 D 7 D 0 D 1 D 1 D 7 D 7 D 0 D 1 D 1 D 2 D 7 D 0 D 1 D 1 D 2 D 7 D 0 D 1 D 1 D 2 D 7 D 0 D 1 D 1 D 1 D 2 D 7 D 0 D 1 D 1 D 1 D 2 D 7 D 0 D 1 D 1 D 1 D 2 D 0 D 1 D 1 D 1 D 2 D 0 D 1 D 1 D 1 D 1 D 1 D 2 D 0 D 7 D 0 D 1 D 1 D 1 D 2 D 0 D 1 D 1 D 1 D 1 D 2 D 0 D 1 D 1 D 1 D 1 D 1 D 1 D 1 D 1 D 1 D 1	COM 46 COM 47
BE	COM 47 COM 48
BE D 3 P 3 D 4 D 5 P6 P 5 D 6 0 P 7 P 7 D 0 P 8 P 9 D 1 P 9 P 4 D 2 P 9 D 1 P 9 P 4 D 2 P 9 D 4 P 9 P 4 D 5 P 6 P 9 D 1 P 9 P 4 D 2 P 1 P 9 D 4 P 9 P 4 P 7 P 9 P 4 P 7 P 9 P 4 P 7 P 9 P 4 P 7 P 9 P 4 P 7 P 9 P 4 P 7 P 9 P 4 P 7 P 9 P 4 P 7 P 9 P 4 P 8 P 1 P 9 P 7 P 9 P 1 P 9 P 1 P 1 P 9 P 1 P 1	COM 49
D4 P4 D5 P6 D6 P7 D7 P7 D0 P7 D1 P7 D2 P7 D4 P7 D2 P7 D4 P7 D5 P6 P7 P7 P7	CON 50
05 06 P5 07 P7 00 0 P7 01 P7 02 P7 03 P4 05 P1 06 P7 07 P7 08 P1 09 P1 01 P7 02 P7 03 P7 04 P7 05 P7 06 P7 07 P7	COM 51 COM 52
D 7 P 7 D 0 0 D 1 0 D 2 0 D 3 0 D 4 0 D 5 0 D 6 0 D 7 0 WM000000000000000000000000000000000000	COM 53
BF D 0 D 1 D 2 D 2 D 3 D 4 D 5 D 6 D 7	CON 54
BF D 1 P 9 D 2 P 9 D 3 P 4 D 4 P 9 D 5 P 9 D 4 P 9 D 5 P 9 D 6 P 9 D 7 P 9 MM00000000000000000000000000000000000	COM 55 COM 56
BF D 3 I I I D 4 D 5 I I I D 5 D 6 PD PD D 7 I I I W1000000000000000000000000000000000000	COM 57
D 4 D 5 P C D 5 D 6 P D D 7 P B P P NM0700 0 + + + + + + + + + + + + + + + + + + +	CON 58
P I 3 I 9 I <td>COM 59 COM 60</td>	COM 59 COM 60
19 7.0 31 7.0 32 7.0 33 7.0	COM 61
COLUMN ADDRESS ADDRESS 77 77 77 77 77	COM 62
MIRINI COLUMN MIRINI MIRINI MIRINI MIRINI	COM 63

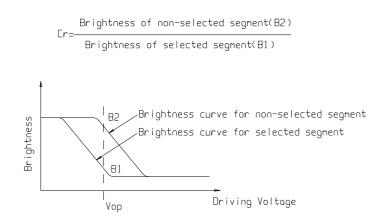
ELECTRO-OPTICAL CHARACTERISTICS ($V_{OP} = 13.8V$, $T_a = 25^{\circ}C$)

Item	Symbol	Condition	Min	Тур	Max	Unit	Remarks	Note
Response time	Tr			314		ms		1
	Tf			112		ms		1
Contrast ratio	Cr			8.4				2
			28			deg	$\varnothing = 90^{\circ}$	3
Viewing angle range	θ	$Cr \ge 2$	24			deg	$\varnothing = 270^{\circ}$	3
			34			deg	$\varnothing = 0^{\circ}$	3
			50			deg	$\varnothing = 180^{\circ}$	3

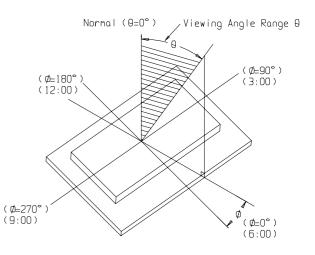
Note1: Definition of response time.



Note2: Definition of contrast ratio 'Cr'



Note3: Definition of viewing angle range ' θ '.



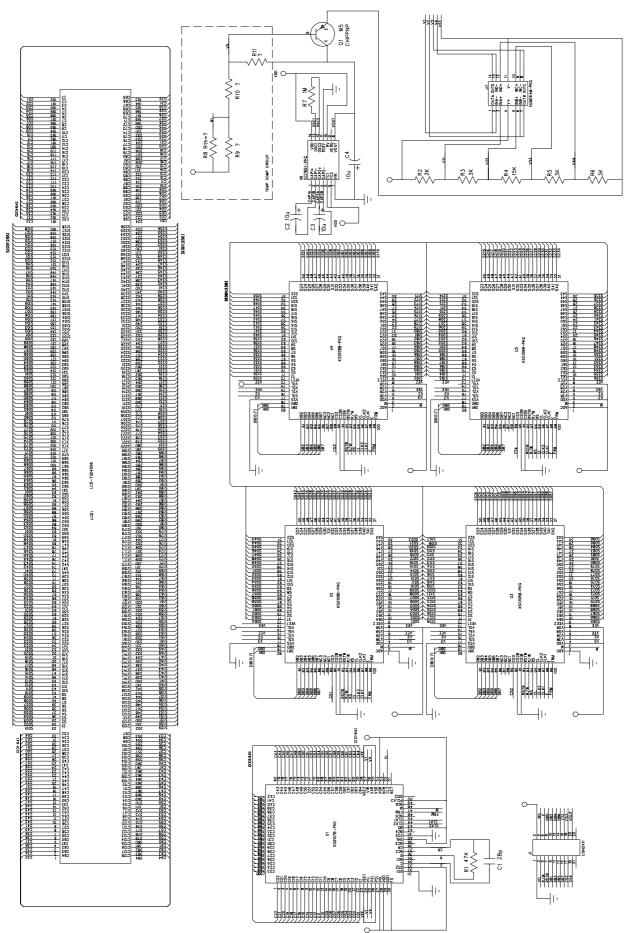
Pin NO.	Symbol	Level	Description
1	VSS	0V	Ground
2	VDD	5.0V	Supply voltage for logic
3	VO		Input voltage for LCD
4	RS	H/L	H : Data, L : Instruction code
5	R/W	H/L	H : Read signal, L : Write signal
6	Е	$H, H \rightarrow L$	Chip enable signal
7	RST	L	Reset signal
8	DB0	H/L	Data bit 0
9	DB1	H/L	Data bit 1
10	DB2	H/L	Data bit 2
11	DB3	H/L	Data bit 3
12	DB4	H/L	Data bit 4
13	DB5	H/L	Data bit 5
14	DB6	H/L	Data bit 6
15	DB7	H/L	Data bit 7
16	CS1	Н	Chip selection for KS0108B(1)
17	CS2	Н	Chip selection for KS0108B(2)
18	CS3	Н	Chip selection for KS0108B(3)
19	CS4	Н	Chip selection for KS0108B(4)
20	VOUT	-10V	Output voltage for LCD
21	NC		No connection
22	NC		No connection

■ INTERFACE PIN CONNECTIONS

■ PART LIST

Part Name	Description	Quantity
IC	KS0108B.PKG	4
IC	KS0107B.PKG	1
IC	SCI7661MOA	1
IC	NJM064M(OP-AMP)	1
LCD	TSD4006-DGFDCN	1
PCB	MPG128128A1-5	1
Frame	MG128128-1	1
Rubber connector	$81.4 \times 3.0 \times 3.2$ mm YS	2
Resistor	47ΚΩ	1
Resistor	3ΚΩ	4
Resistor	15ΚΩ	1
Resistor	1MΩ	1
Capacitor	10µF	3
Capacitor	27pF	1
Transistor	M5	1

CIRCUIT DIAGRAM



■ RELIABILITY

♦ Content of Reliability Test

	Environmental Test									
No.	Test Item	Content of Test	Test Condition	Applicable Standard						
1	High temperature storage	Endurance test applying the high storage temperature for a long time.	60 °C 200 hrs							
2	Low temperature storage	Endurance test applying the low storage temperature for a long time.	-10 °C 200 hrs							
3	High temperature operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	50 °C 200 hrs							
4	Low temperature operation	Endurance test applying the electric stress under low temperature for a long time.	0 °C 200 hrs							
5	High temperature / Humidity storage	Endurance test applying the high temperature and high humidity storage for a long time.	60 °C , 90 %RH 96 hrs	MIL-202E-103B JIS-C5023						
6	High temperature / Humidity operation	Endurance test applying the electric stress (Voltage & Current) and temperature / humidity stress to the element for a long time.	40 °C , 90 %RH 96 hrs	MIL-202E-103B JIS-C5023						
7	Temperature cycle	Endurance test applying the low and high temperature cycle. $\frac{-10^{\circ}C}{30\text{min.}} \rightleftharpoons \frac{25^{\circ}C}{5\text{min.}} \rightleftharpoons \frac{60^{\circ}C}{30\text{min.}}$ 1 cycle	-10°C / 60°C 10 cycles							
		Mechanical Test								
8	Vibration test	Endurance test applying the vibration during transportation and using.	$10 \sim 22 \text{Hz} \rightarrow 1.5 \text{mmp-p}$ $22 \sim 500 \text{Hz} \rightarrow 1.5 \text{G}$ Total 0.5 hrs	MIL-202E-201A JIS-C5025 JIS-C7022-A-10						
9	Shock test	Constructional and mechanical endurance test applying the shock during transportation.	50G half sign wave 11 msedc 3 times of each direction	MIL-202E-213B						
10	Atmospheric pressure test	Endurance test applying the atmospheric pressure during transportation by air.	115 mbar 40 hrs	MIL-202E-105C						
		Others								
11	Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V , RS=1.5 kΩ CS=100 pF 1 time	MIL-883B-3015.1						

*** Supply voltage for logic system = 5V. Supply voltage for LCD system = Operating voltage at 25°C.

♦ Failure Judgement Criterion

Criterion Item		Test Item No.					Failure Judgment Criterion						
	1	2	3	4	5	6	7	8	9	10	11		
Basic specification												Out of the Basic Specification	
Electrical characteristic												Out of the DC and AC Characterstic	
Mechanical characterstic												Out of the Mechanical Specification Color	
												change : Out of Limit Apperance Specification	
Optical characterstic												Out of the Apperance Standard	

QUALITY GUARANTEE

♦ Acceptable Quality Level

Each lot should satisfy the quality level defined as follows.

- Inspection method : MIL-STD-105E LEVEL II Normal one time sampling

- AQL		
Partition	AQL	Definition
A: Major	0.4%	Functional defective as product
B: Minor	1.5%	Satisfy all functions as product but not satisfy cosmetic standard

Definition of 'LOT'

One lot means the delivery quantity to customer at one time.

♦ Conditions of Cosmetic Inspection

• Environmental condition

The inspection should be performed at the 1m of height from the LCD module under 2 pieces of 40W white fluorescent lamps (Normal temperature $20 \sim 25^{\circ}$ C and normal humidity $60 \pm 15\%$ RH).

- Inspection method
 - The visual check should be performed vertically at more than 30cm distance from the LCD panel.
- Driving voltage

The Vo value which the most optimal contrast can be obtained near the specified Vo in the specification. (Within ± 0.5 V of the typical value at 25°C.).

■ INSPECTION CRITERIA

◆ Module Cosmetic Criteria

No. Item	Judgement Criterion	Partition
1 Difference in Spec.	None allowed	Major
2 Pattern peeling	No substrate pattern peeling and floating	Major
3 Soldering defects	No soldering missing	Major
	No soldering bridge	Major
	No cold soldering	Minor
Resist flaw on substrate		Minor
5 Accretion of metallic	No soldering dust	Minor
Foreign matter	No accretion of metallic foreign matters (Not exceed Ø0.2mm)	Minor
6 Stain	No stain to spoil cosmetic badly	Minor
7 Plate discoloring	No plate fading, rusting and discoloring	Minor
8 Solder amount	a. Soldering side of PCB	Minor
	Solder to form a 'Filet'	
1. Lead parts	all around the lead.	
	Solder should not hide the	
	lead form perfectly. (too much)	Í .
	b. Components side	4
	(In case of 'Through Hole PCB')	
	Solder to reach the Components side of PCB.	K >
	bolder to reach the components side of red.	$ X \rangle$
2. Flat packages	Either 'toe' (A) or 'heal' (B) of	Minor
1 0	the lead to be covered by 'Filet'. A A	
		\rightarrow
	Lead form to be assume over	\times
	solder.	> 1
2. (1)		
3. Chips	$(3/2) H \ge h \ge (1/2) H$	Minor
	/////////////////////////////////	1
-f 10		

◆ Screen Cosmetic Criteria (Non-Operating)

No.	Defect	Judgement Criterion							
1	Spots	In accordance with Screen Cost	Minor						
2	Lines	In accordance with Screen Cost	In accordance with Screen Cosmetic Criteria (Operating) No.2.						
3	Bubbles in polarizer	Size : d mm $d \le 0.3$ $0.3 < d \le 1.0$ $1.0 < d \le 1.5$ $1.5 < d$	Acceptable Qty in active area Disregard 3 1 0	Minor					
4	Scratch	In accordance with spots and lines operating cosmetic criteria. When the light reflects on the panel surface, the scratches are not to be remarkable.							
5	Allowable density	Above defects should be separated more than 30mm each other.							
6	Coloration	Not to be noticeable coloration Back-lit type should be judged	Minor						
7	Contamination	Not to be noticeable.	Minor						

◆ Screen Cosmetic Criteria (Operating)

No.	Defect	Judg A) Clear	gement Criterion	Partition
1	Spots		Minor	
		Size : d mm	Acceptable Qty in active area	
		d ≤ 0.1	Disregard	
		$0.1 < d \leq 0.2$	6	
		$0.2 < d \le 0.3$	2	
		0.3 < d	0	
		Note : Including pin holes and de size. B) Unclear	efective dots which must be within one pixel	
		Size : d mm	Acceptable Qty in active area	
		$d \le 0.2$	Disregard	
		$0.2 < d \le 0.5$	6	
		$0.5 < d \le 0.7$	2	
		0.7 < d	0	
2	Lines	A) Clear		Minor
		L 5.0 2.0 (6) Note : () - Acceptable Qty in ac L - Length (mm) W - Width (mm) ∞ - Disregard B) Unclear L 10.0 (6)	(0) See No. 1 0.1 W w w w 0.1 See No. 1 0.3 0.5 W	

'Clear' = The shade and size are not changed by Vo.

'Unclear' = The shade and size are changed by Vo.

◆ Screen Cosmetic Criteria (Operating) (Continued)

No.	Defect	Judgement Criterion	Partition
3	Rubbing line	Not to be noticeable.	
4	Allowable density	Above defects should be separated more than 10mm each other.	Minor
5	Rainbow	Not to be noticeable.	Minor
6	Dot size	To be 95% ~ 105% of the dot size (Typ.) in drawing. Partial defects of each dot (ex. pin-hole) should be treated as 'spot'. (see <i>Screen Cosmetic Criteria (Operating) No.1</i>)	Minor
7	Uneven brightness (only back-lit type module)	 Uneven brightness must be BMAX / BMIN ≤ 2 BMAX : Max. value by measure in 5 points BMIN : Min. value by measure in 5 points Divide active area into 4 vertically and horizontally. Measure 5 points shown in the following figure. 	Minor
		\circ	
		0	
		O : Measuring points	

Note :

(1) Size : d = (long length + short length) / 2

(2) The limit samples for each item have priority.

(3) Complexed defects are defined item by item, but if the number of defects are defined in above table, the total number should not exceed 10.

(4) In case of 'concentration', even the spots or the lines of 'disregarded' size should not allowed. Following three situations should be treated as 'concentration'.

- 7 or over defects in circle of Ø5mm.

- 10 or over defects in circle of Ø10mm.

- 20 or over defects in circle of \emptyset 20mm.

■ PRECAUTIONS FOR USING LCD MODULES

♦ Handing Precautions

(1) The display panel is made of glass. Do not subject it to a mechanical shock by dropping it or impact.

(2) If the display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance contacts your skin or clothes, wash it off using soap and water.

(3) Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.

(4) The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.

(5) If the display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents :

- Isopropyl alcohol
- Ethyl alcohol

(6) Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the following.

- Water
- Ketone
- Aromatic solvents

(7) Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or a current flow in a high-humidity environment.

(8) Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.

(9) Do not attempt to disassemble or process the LCD module.

(10) NC terminal should be open. Do not connect anything.

(11) If the logic circuit power is off, do not apply the input signals.

(12) To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.

- Be sure to ground the body when handling the LCD modules.

- Tools required for assembling, such as soldering irons, must be properly grounded.

- To reduce the amount of static electricity generated, do not conduct assembling and other work under dry conditions.

- The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.

♦ Storage Precautions

When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps. Keep the modules in bags (avoid high temperature / high humidity and low temperatures below 0° C). Whenever possible, the LCD modules should be stored in the same conditions in which they were shipped from our company.

♦ Others

Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.

If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.

To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.

- Exposed area of the printed circuit board.

- Terminal electrode sections.

USING LCD MODULES

◆ Liquid Crystal Display Modules

LCD is composed of glass and polarizer. Pay attention to the following items when handling.

(1) Please keep the temperature within specified range for use and storage. Polarization degradation, bubble generation or polarizer peel-off may occur with high temperature and high humidity.

(2) Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead (glass, tweezers, etc.).

(3) N-hexane is recommended for cleaning the adhesives used to attach front/rear polarizers and reflectors made of organic substances which will be damaged by chemicals such as acetone, toluene, ethanol and isopropylalcohol.

(4) When the display surface becomes dusty, wipe gently with absorbent cotton or other soft material like chamois soaked in petroleum benzin. Do not scrub hard to avoid damaging the display surface.

(5) Wipe off saliva or water drops immediately, contact with water over a long period of time may cause deformation or color fading.

(6) Avoid contacting oil and fats.

(7) Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizers. After products are tested at low temperature they must be warmed up in a container before coming is contacting with room temperature air.

(8) Do not put or attach anything on the display area to avoid leaving marks on.

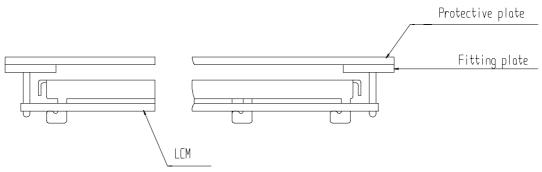
(9) Do not touch the display with bare hands. This will stain the display area and degradate insulation between terminals (some cosmetics are determinated to the polarizers).

(10) As glass is fragile. It tends to become or chipped during handling especially on the edges. Please avoid dropping or jarring.

♦ Installing LCD Modules

The hole in the printed circuit board is used to fix LCM as shown in the picture below. Attend to the following items when installing the LCM.

(1) Cover the surface with a transparent protective plate to protect the polarizer and LC cell.



(2) When assembling the LCM into other equipment, the spacer to the bit between the LCM and the fitting plate should have enough height to avoid causing stress to the module surface, refer to the individual specifications for measurements. The measurement tolerance should be ± 0.1 mm.

◆ Precaution for Handing LCD Modules

Since LCM has been assembled and adjusted with a high degree of precision, avoid applying excessive shocks to the module or making any alterations or modifications to it.

(1) Do not alter, modify or change the the shape of the tab on the metal frame.

(2) Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.

(3) Do not damage or modify the pattern writing on the printed circuit board.

(4) Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal connector.

(5) Except for soldering the interface, do not make any alterations or modifications with a soldering iron.

(6) Do not drop, bend or twist LCM.

◆ Electro-Static Discharge Control

Since this module uses a CMOS LSI, the same careful attention should be paid to electrostatic discharge as for an ordinary CMOS IC.

(1) Make certain that you are grounded when handing LCM.

(2) Before remove LCM from its packing case or incorporating it into a set, be sure the module and your body have the same electric potential.

(3) When soldering the terminal of LCM, make certain the AC power source for the soldering iron does not leak.

(4) When using an electric screwdriver to attach LCM, the screwdriver should be of ground potentiality to minimize as much as possible any transmission of electromagnetic waves produced sparks coming from the commutator of the motor.

(5) As far as possible make the electric potential of your work clothes and that of the work bench the ground potential.

(6) To reduce the generation of static electricity be careful that the air in the work is not too dried. A relative humidity of 50%-60% is recommended.

Precaution for soldering to the LCM

(1) Observe the following when soldering lead wire, connector cable and etc. to the LCM.

- Soldering iron temperature : $280^{\circ}C \pm 10^{\circ}C$.

- Soldering time : 3-4 sec.
- Solder : eutectic solder.

If soldering flux is used, be sure to remove any remaining flux after finishing to soldering operation. (This does not apply in the case of a non-halogen type of flux.) It is recommended that you protect the LCD surface with a cover during soldering to prevent any damage dur to flux spatters.

(2) When soldering the electroluminescent panel and PC board, the panel and board should not be detached more than three times. This maximum number is determined by the temperature and time conditions mentioned above, though there may be some variance depending on the temperature of the soldering iron.

(3) When remove the electoluminescent panel from the PC board, be sure the solder has completely melted, the soldered pad on the PC board could be damaged.

♦ Precautions for Operation

(1) Viewing angle varies with the change of liquid crystal driving voltage (Vo). Adjust Vo to show the best contrast.

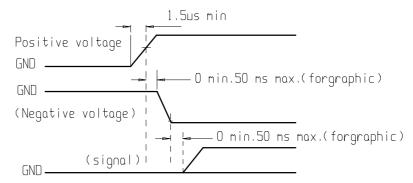
(2) Driving the LCD in the voltage above the limit shortens its life.

(3) Response time is greatly delayed at temperature below the operating temperature range. However, this does not mean the LCD will be out of the order. It will recover when it returns to the specified temperature range.

(4) If the display area is pushed hard during operation, the display will become abnormal. However, it will return to normal if it is turned off and then back on.

(5) Condensation on terminals can cause an electrochemical reaction disrupting the terminal circuit. Therefore, it must be used under the relative condition of 40° C, 50% RH.

(6) When turning the power on, input each signal after the positive/negative voltage becomes stable.



◆ Storage

When storing LCDs as spares for some years, the following precaution are necessary.

(1) Store them in a sealed polyethylene bag. If properly sealed, there is no need for dessicant.

(2) Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0°C and 35°C.

(3) The polarizer surface should not come in contact with any other objects. (We advise you to store them in the container in which they were shipped.)

(4) Environmental conditions :

- Do not leave them for more than 168hrs. at 60°C.

- Should not be left for more than 48hrs. at -20°C.

♦ Safety

(1) It is recommended to crush damaged or unnecessary LCDs into pieces and wash them off with solvents such as acetone and ethanol, which should later be burned.

(2) If any liquid leakes out of a damaged glass cell and comes in contact with the hands, wash off thoroughly with soap and water.

♦ Limited Warranty

Unless agreed between ED and customer, ED will replace or repair any of its LCD modules which are found to be functionally defective when inspected in accordance with ED LCD acceptance standards (copies available upon request) for a period of one year from date of shipments. Cosmetic/visual defects must be returned to ED within 90 days of shipment. Confirmation of such date shall be based on freight documents. The warranty liability of ED limited to repair and/or replacement on the terms set forth above. ED will not be responsible for any subsequent or consequential events.

♦ Return LCM under warranty

No warranty can be granted if the precautions stated above have been disregarded. The typical examples of violations are :

- Broken LCD glass.
- PCB eyelet's damaged or modified.
- PCB conductors damaged.
- Circuit modified in any way, including addition of components.
- PCB tampered with by grinding, engraving or painting varnish.
- soldering to or modifying the bezel in any manner.

Module repairs will be invoiced to the customer upon mutual agreement. Modules must be returned with sufficient description of the failures or defects. Any connectors or cable installed by the customer must be removed completely without damaging the PCB eyelet's, conductors and terminals.